

innin receive

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

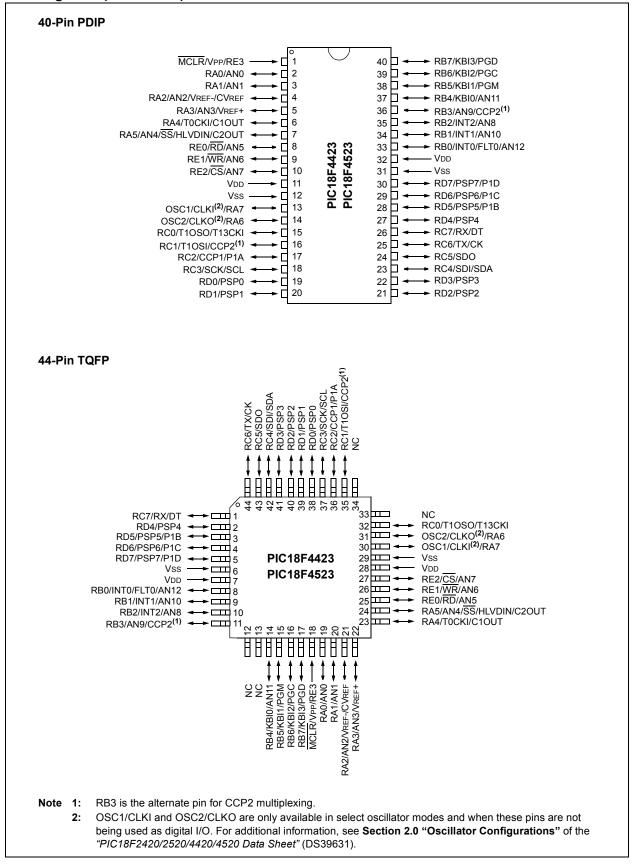
Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f4523-e-pt

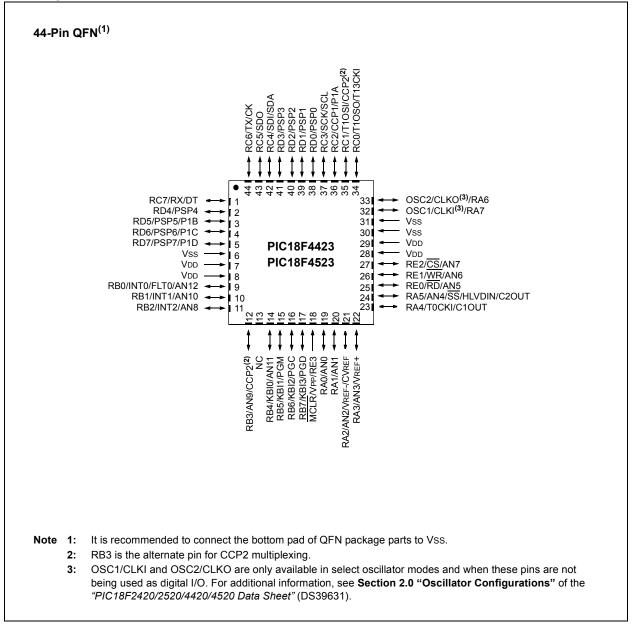
Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Pin Diagrams (Continued)



Pin Diagrams (Continued)



TO OUR VALUED CUSTOMERS

It is our intention to provide our valued customers with the best documentation possible to ensure successful use of your Microchip products. To this end, we will continue to improve our publications to better suit your needs. Our publications will be refined and enhanced as new volumes and updates are introduced.

If you have any questions or comments regarding this publication, please contact the Marketing Communications Department via E-mail at **docerrors@microchip.com** or fax the **Reader Response Form** in the back of this data sheet to (480) 792-4150. We welcome your feedback.

Most Current Data Sheet

To obtain the most up-to-date version of this data sheet, please register at our Worldwide Web site at:

http://www.microchip.com

You can determine the version of a data sheet by examining its literature number found on the bottom outside corner of any page. The last character of the literature number is the version number, (e.g., DS30000A is version A of document DS30000).

Errata

An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

- Microchip's Worldwide Web site; http://www.microchip.com
- Your local Microchip sales office (see last page)

When contacting a sales office, please specify which device, revision of silicon and data sheet (include literature number) you are using.

Customer Notification System

Register on our web site at www.microchip.com to receive the most current information on all of our products.

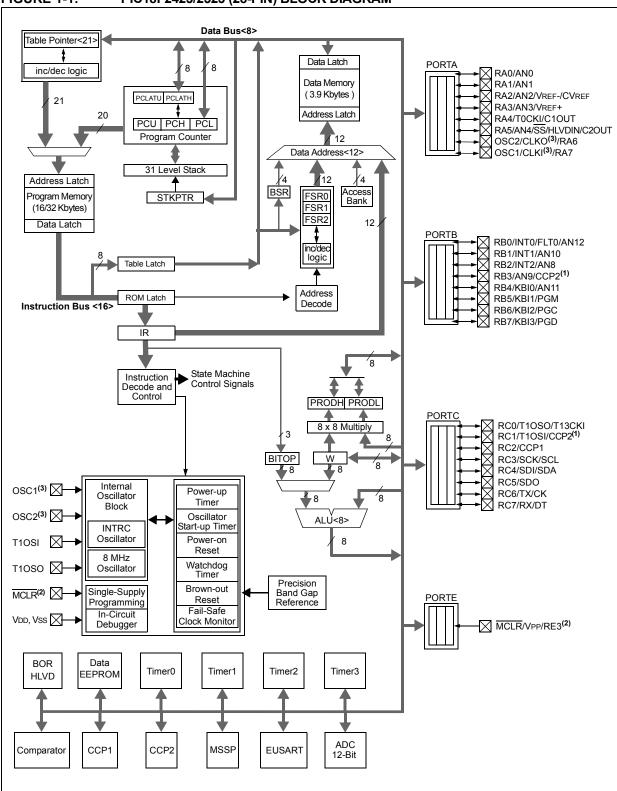


FIGURE 1-1: PIC18F2423/2523 (28-PIN) BLOCK DIAGRAM

Note 1: CCP2 is multiplexed with RC1 when Configuration bit, CCP2MX, is set or RB3 when CCP2MX is not set.

2: RE3 is only available when MCLR functionality is disabled.

3: OSC1/CLKI and OSC2/CLKO are only available in select oscillator modes and when these pins are not being used as digital I/O. For additional information, see Section 2.0 "Oscillator Configurations" of the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631).

TABLE 1-2:	PIC18F2423/2523 PINOUT I/O DESCRIPTIONS
------------	---

	Pin N	umber	Pin	Buffer	
Pin Name	PDIP, SOIC	QFN	Туре		Description
MCLR/VPP/RE3	1	26			Master Clear (input) or programming voltage (input).
MCLR				ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
Vpp			Р		Programming voltage input.
RE3			Ι	ST	Digital input.
OSC1/CLKI/RA7	9	6			Oscillator crystal or external clock input.
OSC1				ST	Oscillator crystal input or external clock source input. ST buffer when configured in RC mode; CMOS otherwise.
CLKI			I	CMOS	External clock source input. Always associated with pin
					function, OSC1. (See related OSC1/CLKI, OSC2/CLKO
RA7			1/0	TTL	pins.) General purpose I/O pin.
OSC2/CLKO/RA6	10	7	1/0	116	
OSC2/CLKO/RA6	10	1	0		Oscillator crystal or clock output. Oscillator crystal output. Connects to crystal or
0002			Ŭ		resonator in Crystal Oscillator mode.
CLKO			0	—	In RC mode, OSC2 pin outputs CLKO, which has 1/4 the
RA6			1/0	TTL	frequency of OSC1 and denotes the instruction cycle rate. General purpose I/O pin.
				116	
	ompatib	•			CMOS = CMOS compatible input or output
		er input	with C	MOS le	
O = Outpu I ² C = I ² C™	it /SMBus				P = Power

 $I^2C = I^2C^{TM}/SMBus$

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

REGISTER 2-2: ADCON1: A/D CONTROL REGISTER	1
--	---

U-0	U-0	R/W-0	R/W-0	R/W-0 ⁽¹⁾	R/W ⁽¹⁾	R/W ⁽¹⁾	R/W ⁽¹⁾
—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	1 as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6	Unimplemented: Read as '0'
---------	----------------------------

bit 5	VCFG1: Voltage Reference Configuration bit (VREF- source)
	1 = VREF- (AN2)
	0 = Vss
bit 4	VCFG0: Voltage Reference Configuration bit (VREF+ source)
	1 = VREF+ (AN3)
	0 = VDD

bit 3-0 **PCFG<3:0>:** A/D Port Configuration Control bits:

PCFG<3:0>	AN12	AN11	AN10	AN9	AN8	AN 7 ⁽²⁾	AN6 ⁽²⁾	AN5 ⁽²⁾	AN4	AN3	AN2	AN1	ANO
₀₀₀₀ (1)	А	А	Α	Α	Α	Α	Α	Α	Α	Α	Α	Α	Α
0001	Α	А	А	Α	Α	Α	Α	Α	Α	Α	Α	Α	Α
0010	Α	А	А	Α	Α	Α	Α	Α	Α	Α	Α	Α	Α
0011	D	А	Α	Α	Α	Α	Α	Α	Α	А	Α	Α	Α
0100	D	D	А	Α	Α	Α	Α	Α	Α	А	Α	Α	Α
0101	D	D	D	Α	Α	Α	Α	Α	Α	Α	Α	Α	Α
0110	D	D	D	D	А	Α	Α	Α	Α	А	Α	Α	Α
0111(1)	D	D	D	D	D	А	Α	Α	А	А	А	А	А
1000	D	D	D	D	D	D	Α	Α	Α	Α	Α	Α	Α
1001	D	D	D	D	D	D	D	Α	Α	Α	Α	Α	Α
1010	D	D	D	D	D	D	D	D	Α	А	Α	Α	Α
1011	D	D	D	D	D	D	D	D	D	А	Α	Α	Α
1100	D	D	D	D	D	D	D	D	D	D	Α	Α	Α
1101	D	D	D	D	D	D	D	D	D	D	D	А	Α
1110	D	D	D	D	D	D	D	D	D	D	D	D	Α
1111	D	D	D	D	D	D	D	D	D	D	D	D	D
A = Analog input D = Digital I/O													

Note 1: The POR value of the PCFG bits depends on the value of the PBADEN Configuration bit. When PBADEN = 1, PCFG<3:0> = 0000; when PBADEN = 0, PCFG<3:0> = 0111.

2: AN5 through AN7 are only available on PIC18F4423/4523 devices.

PIC18F2423/2523/4423/4523

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM		ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0
bit 7							bit (
Legend:							
R = Readabl	e bit	W = Writable	bit	U = Unimplen	nented bit, rea	d as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle		x = Bit is unki	nown
bit 7	ADFM: A/D F	Result Format S	Select bit				
	1 = Right just 0 = Left justifi						
bit 6	•	ted: Read as '	0'				
bit 5-3	ACQT<2:0>:	A/D Acquisitio	n Time Select	t bits			
	111 = 20 T AD)					
	110 = 16 Tad)					
	101 = 12 TAD)					
	100 = 8 T AD						
	011 = 6 TAD 010 = 4 TAD						
	010 = 4 TAD 001 = 2 TAD						
	000 = 0 TAD ^{(*}	1)					
bit 2-0	ADCS<2:0>:	A/D Conversio	n Clock Sele	ct bits			
	111 = FRC (c	lock derived fro	om A/D RC os	scillator) ⁽¹⁾			
	110 = Fosc/6			,			
	101 = Fosc/*	16					
	100 = Fosc/4			(4)			
		lock derived fro	om A/D RC os	scillator) ⁽¹⁾			
	010 = Fosc/3						
	001 = Fosc/8 000 = Fosc/2	5					

REGISTER 2-3: ADCON2: A/D CONTROL REGISTER 2

Note 1: If the A/D FRC clock source is selected, a delay of one TcY (instruction cycle) is added before the A/D clock starts. This allows the SLEEP instruction to be executed before starting a conversion.

The analog reference voltage is software selectable to either the device's positive and negative supply voltage (VDD and Vss), or the voltage level on the RA3/AN3/ VREF+ and RA2/AN2/VREF-/CVREF pins.

The A/D Converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The output of the sample and hold is the input into the converter, which generates the result via successive approximation.

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off and any conversion in progress is aborted.

Each port pin associated with the A/D Converter can be configured as an analog input or as a digital I/O. The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is <u>loaded</u> into the ADRESH:ADRESL register pair, the GO/DONE bit (ADCON0<1>) is cleared and A/D Interrupt Flag bit, ADIF, is set.

The block diagram of the A/D module is shown in Figure 2-1.

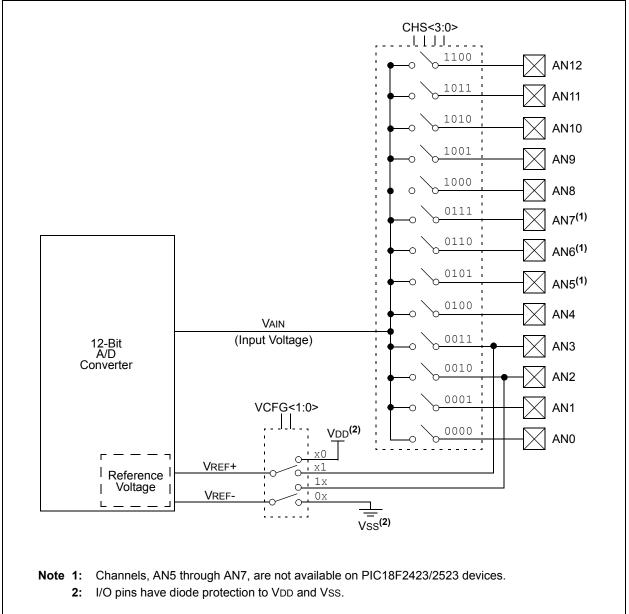


FIGURE 2-1: A/D BLOCK DIAGRAM

2.1 A/D Acquisition Requirements

For the A/D Converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 2-3.

The source impedance (Rs) and the internal sampling switch (Rss) impedance directly affect the time required to charge the capacitor, CHOLD. The sampling switch (Rss) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). The maximum recommended impedance for analog sources is 2.5 k Ω .

After the analog input channel is selected (changed), the channel must be sampled for at least the minimum acquisition time before starting a conversion.

Note:	When	the	conversion	is	started,	the
	holding	g capa	acitor is disco	nne	ected from	the
	input p	in.				

EQUATION 2-1: ACQUISITION TIME

To calculate the minimum acquisition time, Equation 2-1 may be used. This equation assumes that 1/2 LSb error is used (4,096 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

Example 2-3 shows the calculation of the minimum required acquisition time, TACQ. This calculation is based on the application system assumptions shown in Table 2-1:

CHOLD	=	25 pF
Rs	=	2.5 kΩ
Conversion Error	\leq	1/2 LSb
Vdd	=	$3V \rightarrow Rss = 4 \ k\Omega$
Temperature	=	85°C (system maximum)

TABLE 2-1:	TACQ ASSUMPTIONS
IADLL 2-I.	

TACQ	=	Amplifier Settling Time + Holding Capacitor Charging Time + Temperature Coefficient
	=	TAMP + TC + TCOFF

EQUATION 2-2: A/D MINIMUM CHARGING TIME

 $VHOLD = (VREF - (VREF/4096)) \cdot (1 - e^{(-TC/CHOLD(RIC + RSS + RS))})$ or $TC = -(CHOLD)(RIC + RSS + RS) \ln(1/4096)$

EQUATION 2-3: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

TACQ	=	TAMP + TC + TCOFF
TAMP	=	0.2 μs
TCOFF	=	(Temp – 25°C)(0.02 μs/°C) (85°C – 25°C)(0.02 μs/°C) 1.2 μs
Tempera	ture c	oefficient is only required for temperatures $> 25^{\circ}$ C. Below 25°C, TCOFF = 0 ms.
ТС	=	-(CHOLD)(RIC + RSS + RS) $\ln(1/4095) \mu s$ -(25 pF) (1 k Ω + 4 k Ω + 2.5 k Ω) ln(0.0004883) μs 1.56 μs
TACQ	=	0.2 μs + 1.56 μs + 1.2 μs 2.96 μs

2.2 Selecting and Configuring Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set. It also gives users the option of having an automatically determined acquisition time.

Acquisition time may be set with the ACQT<2:0> bits (ADCON2<5:3>), which provide a range of 2 to 20 TAD. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

Manual acquisition time is <u>selected</u> when ACQT<2:0> = 0.00. When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This option is also the default Reset state of the ACQT<2:0> bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

2.3 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 13 TAD per 12-bit conversion. The source of the A/D conversion clock is software selectable.

There are seven possible options for TAD:

- 2 Tosc
- 32 Tosc
 64 Tosc
- 4 Tosc
- Internal RC Oscillator
- 8 Tosc 16 Tosc
 -)SC

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible, but greater than the minimum TAD. (For more information, see parameter 130 on page 41.)

Table 2-2 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

A/D Clock So	Assumes TAD Min. = 0.8 μs			
Operation	ADCS<2:0>	Maximum Fosc		
2 Tosc	000	2.50 MHz		
4 Tosc	100	5.00 MHz		
8 Tosc	001	10.00 MHz		
16 Tosc	101	20.00 MHz		
32 Tosc	010	40.00 MHz		
64 Tosc	110	40.00 MHz		
RC ⁽²⁾	x11	1.00 MHz ⁽¹⁾		

TABLE 2-2:TAD vs. DEVICE OPERATING FREQUENCIES

Note 1: The RC source has a typical TAD time of 2.5 μ s.

2: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or a Fosc divider should be used instead; otherwise, the A/D accuracy specification may not be met.

2.4 Operation in Power-Managed Modes

The selection of the automatic acquisition time and A/D conversion clock is determined in part by the clock source and frequency while in a power-managed mode.

If the A/D is expected to operate while the device is in a power-managed mode, the ADCS<2:0> bits in ADCON2 should be updated in accordance with the clock source to be used. The ACQT<2:0> bits do not need to be adjusted as the ADCS<2:0> bits adjust the TAD time for the new clock speed. After entering the mode, an A/D acquisition or conversion may be started. Once started, the device should continue to be clocked by the same clock source until the conversion has been completed.

If desired, the device may be placed into the corresponding Idle mode during the conversion. If the device clock frequency is less than 1 MHz, the A/D RC clock source should be selected.

Operation in Sleep mode requires the A/D FRC clock to be selected. If bits, ACQT<2:0>, are set to '000' and a conversion is started, the conversion will be delayed one instruction cycle to allow execution of the SLEEP instruction and entry to Sleep mode. The IDLEN bit (OSCCON<7>) must have already been cleared prior to starting the conversion.

2.5 Configuring Analog Port Pins

The ADCON1, TRISA, TRISB and TRISE registers all configure the A/D port pins. The port pins needed as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS<3:0> bits and the TRIS bits.

- Note 1: When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Analog conversion on pins configured as digital pins can be performed. The voltage on the pin will be accurately converted.
 - 2: Analog levels on any pin defined as a digital input may cause the digital input buffer to consume current out of the device's specification limits.
 - **3:** The PBADEN bit in Configuration Register 3H configures PORTB pins to reset as analog or digital pins by controlling how the PCFG<3:0> bits in ADCON1 are reset.

2.8 Use of the CCP2 Trigger

An A/D conversion can be started by the Special Event Trigger of the CCP2 module. This requires that the CCP2M<3:0> bits (CCP2CON<3:0>) be programmed as '1011' and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/DONE bit will be set, starting the A/D acquisition and conversion, and the Timer1 (or Timer3) counter will be reset to zero. Timer1 (or Timer3) is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving ADRESH:ADRESL to the desired location). The appropriate analog input channel must be selected and the minimum acquisition period is either timed by the user or an appropriate TACQ time is selected before the Special Event Trigger sets the GO/DONE bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), the Special Event Trigger will be ignored by the A/D module, but will still reset the Timer1 (or Timer3) counter.

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	(Note 4)
PIR1	PSPIF ⁽¹⁾	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	(Note 4)
PIE1	PSPIE ⁽¹⁾	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	(Note 4)
IPR1	PSPIP ⁽¹⁾	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	(Note 4)
PIR2	OSCFIF	CMIF	_	EEIF	BCLIF	HLVDIF	TMR3IF	CCP2IF	(Note 4)
PIE2	OSCFIE	CMIE	_	EEIE	BCLIE	HLVDIE	TMR3IE	CCP2IE	(Note 4)
IPR2	OSCFIP	CMIP	_	EEIP	BCLIP	HLVDIP	TMR3IP	CCP2IP	(Note 4)
ADRESH	A/D Result Register High Byte						(Note 4)		
ADRESL	A/D Result	Register Lov	w Byte						(Note 4)
ADCON0	—	_	CHS3	CHS2	CHS1	CHS0	GO/DONE	ADON	(Note 4)
ADCON1	_	_	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	(Note 4)
ADCON2	ADFM	—	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0	(Note 4)
PORTA	RA7 ⁽²⁾	RA6 ⁽²⁾	RA5	RA4	RA3	RA2	RA1	RA0	(Note 4)
TRISA	TRISA7 ⁽²⁾ TRISA6 ⁽²⁾ PORTA Data Direction Control Register						(Note 4)		
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	(Note 4)
TRISB	PORTB Data Direction Control Register						(Note 4)		
LATB	PORTB Data Latch Register (Read and Write to Data Latch)						(Note 4)		
PORTE ⁽¹⁾	—	—	_	_	RE3 ⁽³⁾	RE2	RE1	RE0	(Note 4)
TRISE ⁽¹⁾	IBF	OBF	IBOV	PSPMODE	—	TRISE2	TRISE1	TRISE0	(Note 4)
LATE ⁽¹⁾	_	_	_	_		PORTE D	ata Latch Re	egister	(Note 4)

 TABLE 2-3:
 REGISTERS ASSOCIATED WITH A/D OPERATION

Legend: — = unimplemented, read as '0'. Shaded cells are not used for A/D conversion.

Note 1: These registers and/or bits are not implemented on PIC18F2423/2523 devices and are read as '0'.

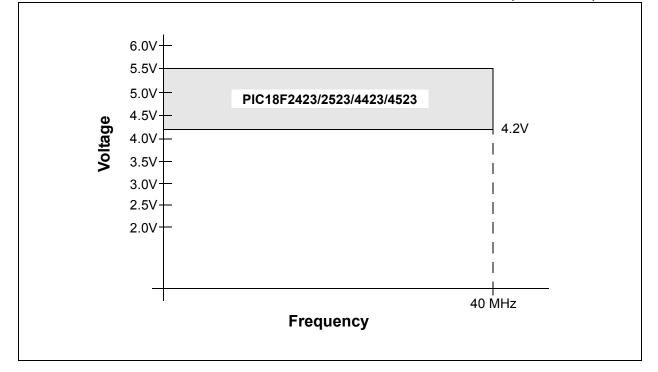
2: PORTA<7:6> and their direction bits are individually configured as port pins based on various primary oscillator modes. When disabled, these bits read as '0'.

3: RE3 port bit is available only as an input pin when the MCLRE Configuration bit is '0'.

4: For these Reset values, see Section 4.0 "Reset" of the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631).

PIC18F2423/2523/4423/4523





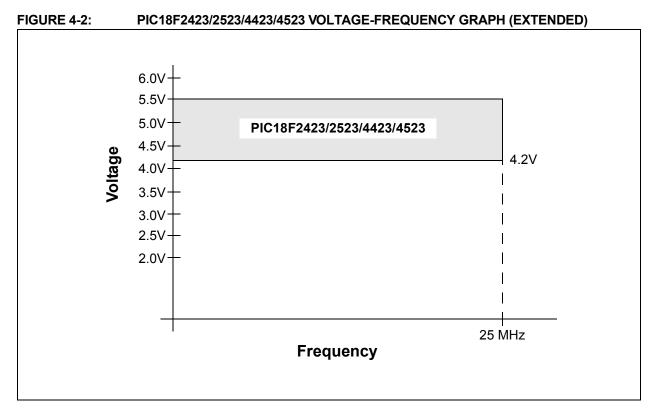


TABLE 4-1:A/D CONVERTER CHARACTERISTICS: PIC18F2423/2523/4423/4523 (INDUSTRIAL)PIC18LF2423/2523/4423/4523 (INDUSTRIAL)

Param No.	Sym	Characteristic	Min	Тур	Max	Units	Conditions	
A01	NR	Resolution	—	_	12	bit		$\Delta \text{VREF} \geq 3.0 \text{V}$
A03	EIL	Integral Linearity Error	—	<±1	±2.0	LSB	VDD = 3.0V	$\Delta \text{VREF} \geq 3.0 \text{V}$
			—	_	±2.0	LSB	VDD = 5.0V	
A04	Edl	Differential Linearity Error	—	<±1	+1.5/-1.0	LSB	VDD = 3.0V	$\Delta \text{VREF} \geq 3.0 \text{V}$
			—	_	+1.5/-1.0	LSB	VDD = 5.0V	
A06	EOFF	Offset Error	—	<±1	±5	LSB	VDD = 3.0V	$\Delta VREF \ge 3.0V$
			—	_	±3	LSB	VDD = 5.0V	
A07	Egn	Gain Error	—	<±1	±1.25	LSB	VDD = 3.0V	$\Delta \text{VREF} \geq 3.0 \text{V}$
			_	_	±2.00	LSB	VDD = 5.0V	
A10	—	Monotonicity	Guaranteed ⁽¹⁾			—		$Vss \leq Vain \leq Vref$
A20	$\Delta VREF$	Reference Voltage Range (VREFH – VREFL)	3	—	Vdd – Vss	V		For 12-bit resolution.
A21	VREFH	Reference Voltage High	Vss + 3.0V	_	VDD + 0.3V	V		For 12-bit resolution.
A22	VREFL	Reference Voltage Low	Vss – 0.3V	_	VDD - 3.0V	V	For 12-bit resolution.	
A25	Vain	Analog Input Voltage	VREFL	_	VREFH	V		
A30	Zain	Recommended Impedance of Analog Voltage Source	—	—	2.5	kΩ		
A50	IREF	VREF Input Current ⁽²⁾		_	5 150	μΑ μΑ		During VAIN acquisition. During A/D conversion cycle.

Note 1: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

2: VREFH current is from the RA3/AN3/VREF+ pin or VDD, whichever is selected as the VREFH source. VREFL current is from the RA2/AN2/VREF-/CVREF pin or VSS, whichever is selected as the VREFL source.

NOTES:

5.0 PACKAGING INFORMATION

For packaging information, see **Section 28.0 "Packaging Information"** in the *"PIC18F2420/2520/4420/4520 Data Sheet"* (DS39631).

NOTES:

APPENDIX E: MIGRATION FROM MID-RANGE TO ENHANCED DEVICES

A detailed discussion of the differences between the mid-range MCU devices (i.e., PIC16CXXX) and the enhanced devices (i.e., PIC18FXXX) is provided in *AN716, "Migrating Designs from PIC16C74A/74B to PIC18C442"*. The changes discussed, while device specific, are generally applicable to all mid-range to enhanced device migrations.

This Application Note is available as Literature Number DS00716.

APPENDIX F: MIGRATION FROM HIGH-END TO ENHANCED DEVICES

A detailed discussion of the migration pathway and differences between the high-end MCU devices (i.e., PIC17CXXX) and the enhanced devices (i.e., PIC18FXXX) is provided in *AN726, "PIC17CXXX to PIC18CXXX Migration*". This Application Note is available as Literature Number DS00726.

READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this document.

To:	Technical Publications Manager	Total Pages Sent
RE:	Reader Response	
Fron	n: Name	
	Company	
	Address	<u>.</u>
	City / State / ZIP / Country	
	Telephone: ()	FAX: ()
Appl	ication (optional):	
Wou	ld you like a reply?YN	
Devi	ce: PIC18F2423/2523/4423/4523	Literature Number: DS39755C
Que	stions:	
1. \	What are the best features of this doc	ument?
-		
-		
2. I	How does this document meet your h	ardware and software development needs?
-		
-		
3. I	Do you find the organization of this do	ocument easy to follow? If not, why?
-		
-	Meet additions to the desument days	withink would appear the structure and subject?
4. \	what additions to the document do yo	ou think would enhance the structure and subject?
-		
5. \	What deletions from the document co	uld be made without affecting the overall usefulness?
0.		
-		
6. I	s there any incorrect or misleading in	formation (what and where)?
-		
7. I	How would you improve this documer	nt?
-		
_		



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support: http://support.microchip.com Web Address: www.microchip.com

Atlanta Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Boston Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL Tel: 630-285-0071 Fax: 630-285-0075

Cleveland Independence, OH Tel: 216-447-0464 Fax: 216-447-0643

Dallas Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Kokomo Kokomo, IN Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

Santa Clara Santa Clara, CA Tel: 408-961-6444 Fax: 408-961-6445

Toronto Mississauga, Ontario, Canada Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office Suites 3707-14, 37th Floor Tower 6, The Gateway Harbour City, Kowloon Hong Kong Tel: 852-2401-1200 Fax: 852-2401-3431

Australia - Sydney Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing Tel: 86-10-8528-2100 Fax: 86-10-8528-2104

China - Chengdu Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Hong Kong SAR Tel: 852-2401-1200 Fax: 852-2401-3431

China - Nanjing Tel: 86-25-8473-2460

Fax: 86-25-8473-2470 China - Qingdao

Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen Tel: 86-755-8203-2660 Fax: 86-755-8203-1760

China - Wuhan Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xiamen Tel: 86-592-2388138 Fax: 86-592-2388130

China - Xian Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

China - Zhuhai Tel: 86-756-3210040 Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore Tel: 91-80-3090-4444 Fax: 91-80-3090-4080

India - New Delhi Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Yokohama Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea - Daegu Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu Tel: 886-3-6578-300 Fax: 886-3-6578-370

Taiwan - Kaohsiung Tel: 886-7-536-4818 Fax: 886-7-536-4803

Taiwan - Taipei Tel: 886-2-2500-6610 Fax: 886-2-2508-0102

Thailand - Bangkok Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels Tel: 43-7242-2244-39 Fax: 43-7242-2244-393 Denmark - Copenhagen Tel: 45-4450-2828 Fax: 45-4485-2829

France - Paris Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Munich Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy - Milan Tel: 39-0331-742611 Fax: 39-0331-466781

Netherlands - Drunen Tel: 31-416-690399 Fax: 31-416-690340

Spain - Madrid Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

UK - Wokingham Tel: 44-118-921-5869 Fax: 44-118-921-5820

03/26/09